



RF360  
Europe GmbH

## Data sheet

SAW duplexer  
Automotive telematics  
LTE band 2

Series/type: B4431  
Ordering code: B39202B4431P810

Date: June 12, 2018  
Version: 2.1

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A Qualcomm – TDK Joint Venture

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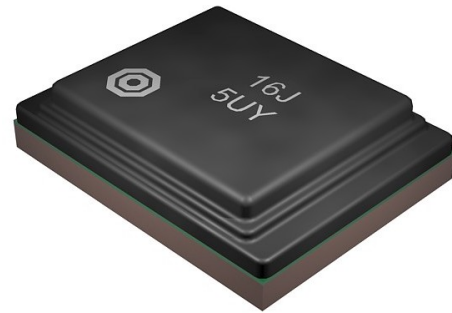
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## 1 Application

- Low-loss SAW duplexer for band 2 systems
- Low insertion attenuation
- Low amplitude ripple
- High isolation between Tx and Rx

## 2 Features

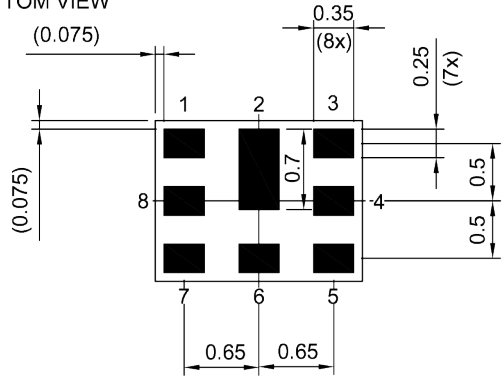
- Package size 1.8±0.1 mm × 1.4±0.1 mm
- Package height 0.45 mm (max.)
- Approximate weight 4 mg
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Filter surface passivated
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 2a (MSL2a)
- AEC-Q200 qualified component family  
(Grade 3: -40 °C to +85 °C)



**Figure 1:** Picture of component with example of product marking.

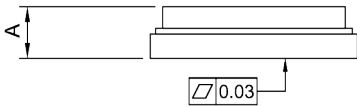
3 Package

BOTTOM VIEW

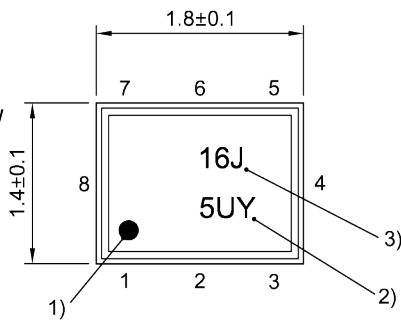


Pad and Pitch Tolerance ±0.05

SIDE VIEW

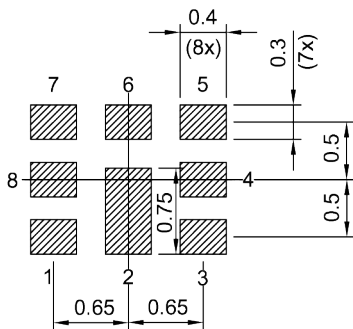


TOP VIEW



- 1) Marking for pad number 1
- 2) Example of encoded lot number
- 3) Example of encoded filter type number

Land pattern  
THRU VIEW



Landing pad tolerance -0.02

4 Pin configuration

- 1 RX
- 3 TX
- 6 ANT
- 2, 4, 5, 7, 8 Ground

Figure 2: Drawing of package with package height A = 0.45 mm (max.). See Sec. Package information (p. 21).

5 Matching circuit

- $L_{p6} = 3.7 \text{ nH}$

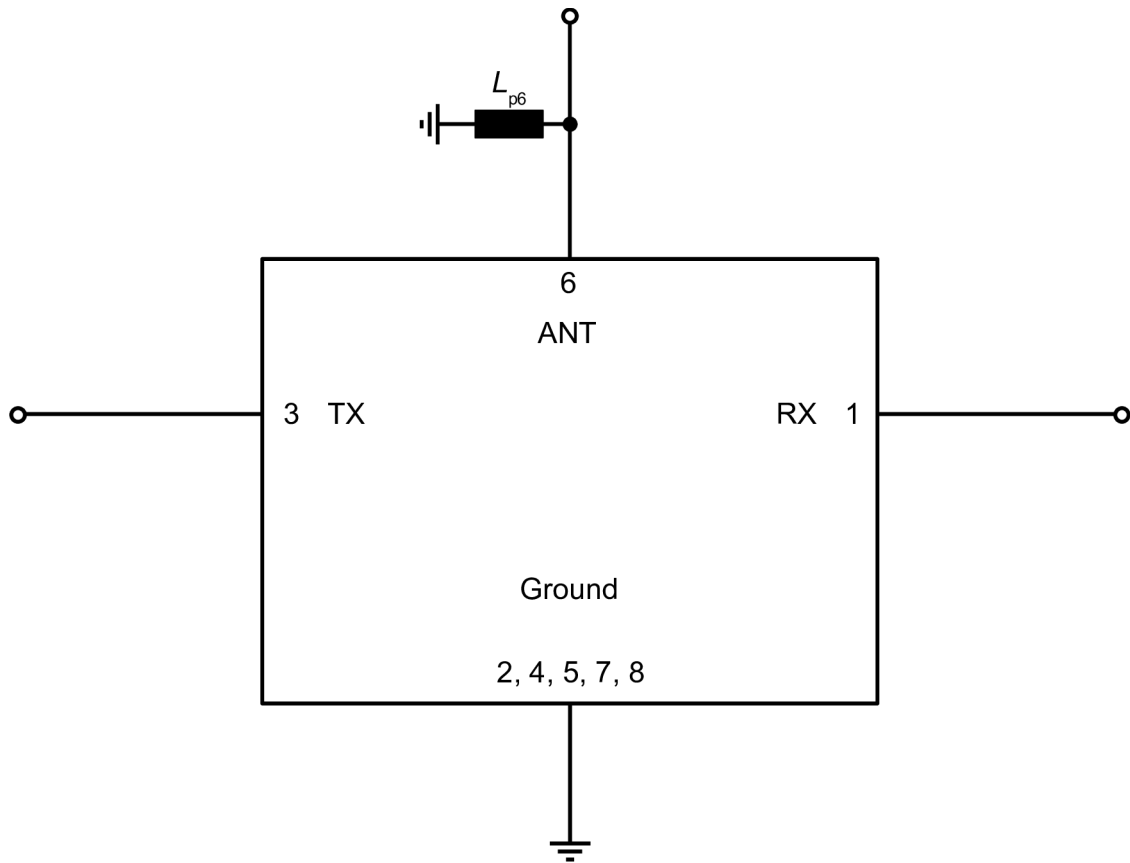


Figure 3: Schematic of matching circuit.



## 6 Characteristics

### 6.1 TX – ANT

Temperature range for specification	$T_{SPEC}$	= -30 °C ... +85 °C
TX terminating impedance	$Z_{TX}$	= 50 $\Omega$
ANT terminating impedance	$Z_{ANT}$	= 50 $\Omega$ with par. 3.7 nH <sup>1)</sup>
RX terminating impedance	$Z_{RX}$	= 50 $\Omega$

Characteristics TX – ANT				min. for $T_{SPEC}$	typ. @ +25 °C	max. for $T_{SPEC}$	
<b>Center frequency</b>			$f_C$	—	1880	—	MHz
<b>Maximum insertion attenuation</b>							
	1850... 1910	MHz	$\alpha_{INT,max}^{2)}$	—	1.9	2.5 <sup>3)</sup>	dB
	1850... 1910	MHz	$\alpha_{INT,max}^{2)}$	—	1.9	2.9	dB
	1850.24... 1909.76	MHz	$\alpha_{max}$	—	2.0	3.9	dB
<b>Amplitude ripple (p-p)</b>			$\Delta\alpha_{INT}^{2)}$				
	1850... 1910	MHz		—	1.0	2.5	dB
<b>Maximum VSWR</b>			$VSWR_{max}$				
@ TX port	1850.24... 1909.76	MHz		—	1.6	2.0	
@ ANT port	1850.24... 1909.76	MHz		—	1.4	2.0	
<b>Minimum attenuation</b>							
	100... 894	MHz	$\alpha_{min}$	37	40	—	dB
	1226... 1250	MHz	$\alpha_{min}$	30	35	—	dB
	1559... 1680	MHz	$\alpha_{min}$	30	35	—	dB
	1930... 1990	MHz	$\alpha_{INT,min}^{2)}$	45 <sup>3)</sup>	49	—	dB
	1930... 1990	MHz	$\alpha_{INT,min}^{2)}$	43	49	—	dB
	1930.24... 1989.76	MHz	$\alpha_{min}$	36	47	—	dB
	2010... 2025	MHz	$\alpha_{min}$	20	37	—	dB
	2110... 2155	MHz	$\alpha_{min}$	30	36	—	dB
	2400... 2500	MHz	$\alpha_{min}$	35	40	—	dB
	3690... 3830	MHz	$\alpha_{min}$	21	26	—	dB
	5150... 5850	MHz	$\alpha_{min}$	17	24	—	dB

<sup>1)</sup> See Sec. Matching circuit (p. 6).

<sup>2)</sup> Integrated attenuation  $\alpha_{INT}$ : Averaged power  $|S_{ij}|^2$  over the center 4.5 MHz of LTE 5 MHz (25 RB) channels.

<sup>3)</sup> Valid for temperature  $T = -10$  °C...+55 °C.

## 6.2 ANT – RX

Temperature range for specification	$T_{SPEC}$	= -30 °C ... +85 °C
TX terminating impedance	$Z_{TX}$	= 50 $\Omega$
ANT terminating impedance	$Z_{ANT}$	= 50 $\Omega$ with par. 3.7 nH <sup>1)</sup>
RX terminating impedance	$Z_{RX}$	= 50 $\Omega$

Characteristics ANT – RX				min. for $T_{SPEC}$	typ. @ +25 °C	max. for $T_{SPEC}$	
<b>Center frequency</b>			$f_C$	—	1960	—	MHz
<b>Maximum insertion attenuation</b>							
	1930... 1990	MHz	$\alpha_{INT,max}^{2)}$	—	2.4	3.1 <sup>3)</sup>	dB
	1930... 1990	MHz	$\alpha_{INT,max}^{2)}$	—	2.4	3.3	dB
	1930.24... 1989.76	MHz	$\alpha_{max}$	—	2.7	4.4	dB
<b>Amplitude ripple (p-p)</b>			$\Delta\alpha_{INT}^{2)}$				
	1930.24... 1990	MHz		—	1.0	2.5	dB
<b>Maximum VSWR</b>			VSWR <sub>max</sub>				
@ ANT port	1930.24... 1989.76	MHz		—	1.8	2.1	
@ RX port	1930.24... 1989.76	MHz		—	1.9	2.2	
<b>Minimum attenuation</b>							
	80	MHz	$\alpha_{min}$	50	70	—	dB
	100... 700	MHz	$\alpha_{min}$	45	63	—	dB
	700... 1850	MHz	$\alpha_{min}$	40	53	—	dB
	1850... 1910	MHz	$\alpha_{INT,min}^{2)}$	50 <sup>3)</sup>	53	—	dB
	1850... 1910	MHz	$\alpha_{INT,min}^{2)}$	45	53	—	dB
	1850.24... 1909.76	MHz	$\alpha_{min}$	37	52	—	dB
	2050... 2075	MHz	$\alpha_{min}$	30	37	—	dB
	2075... 2400	MHz	$\alpha_{min}$	35	47	—	dB
	2400... 2550	MHz	$\alpha_{min}$	40	53	—	dB
	2550... 3000	MHz	$\alpha_{min}$	33	49	—	dB
	3000... 4500	MHz	$\alpha_{min}$	38	45	—	dB
	4500... 6000	MHz	$\alpha_{min}$	32	42	—	dB

<sup>1)</sup> See Sec. Matching circuit (p. 6).

<sup>2)</sup> Integrated attenuation  $\alpha_{INT}$ : Averaged power  $|S_{ij}|^2$  over the center 4.5 MHz of LTE 5 MHz (25 RB) channels.

<sup>3)</sup> Valid for temperature  $T = -10$  °C...+55 °C.

### 6.3 TX – RX

Temperature range for specification	$T_{SPEC}$	= -30 °C ... +85 °C
TX terminating impedance	$Z_{TX}$	= 50 $\Omega$
ANT terminating impedance	$Z_{ANT}$	= 50 $\Omega$ with par. 3.7 nH <sup>1)</sup>
RX terminating impedance	$Z_{RX}$	= 50 $\Omega$

Characteristics TX – RX				min. for $T_{SPEC}$	typ. @ +25 °C	max. for $T_{SPEC}$	
<b>Minimum isolation</b>							
	1574... 1577	MHz	$\alpha_{min}$	40	60	—	dB
	1850... 1910	MHz	$\alpha_{INT,min}^{2)}$	53 <sup>3)</sup>	56	—	dB
	1850... 1910	MHz	$\alpha_{INT,min}^{2)}$	50	56	—	dB
	1850.24... 1909.76	MHz	$\alpha_{min}$	42	54	—	dB
	1930... 1990	MHz	$\alpha_{INT,min}^{2)}$	49 <sup>3)</sup>	54	—	dB
	1930... 1990	MHz	$\alpha_{INT,min}^{2)}$	46	54	—	dB
	1930.24... 1989.76	MHz	$\alpha_{min}$	35	52	—	dB
	3700... 3820	MHz	$\alpha_{min}$	20	51	—	dB
	5550... 5850	MHz	$\alpha_{min}$	20	46	—	dB

<sup>1)</sup> See Sec. Matching circuit (p. 6).

<sup>2)</sup> Integrated attenuation  $\alpha_{INT}$ : Averaged power  $|S_{ij}|^2$  over the center 4.5 MHz of LTE 5 MHz (25 RB) channels.

<sup>3)</sup> Valid for temperature  $T = -10$  °C...+55 °C.

## 7 Maximum ratings

Operable temperature	$T_{OP} = -40\text{ °C} \dots +85\text{ °C}$	
Storage temperature	$T_{STG}^{1)} = -40\text{ °C} \dots +85\text{ °C}$	
DC voltage	$ V_{DC} ^{2)} = 0\text{ V}$	
Input power	$P_{IN}$	
@ TX port: 1850 ... 1910 MHz	29 dBm	Continuous wave for 500 h @ 50 °C.
@ TX port: 1850 ... 1910 MHz	27.5 dBm	Continuous wave for 5000 h @ 50 °C.

<sup>1)</sup> Not valid for packaging material. Storage temperature for packaging material is -25 °C to +40 °C.

<sup>2)</sup> In case of applied DC voltage blocking capacitors are mandatory.

8 Transmission coefficients

8.1 TX – ANT

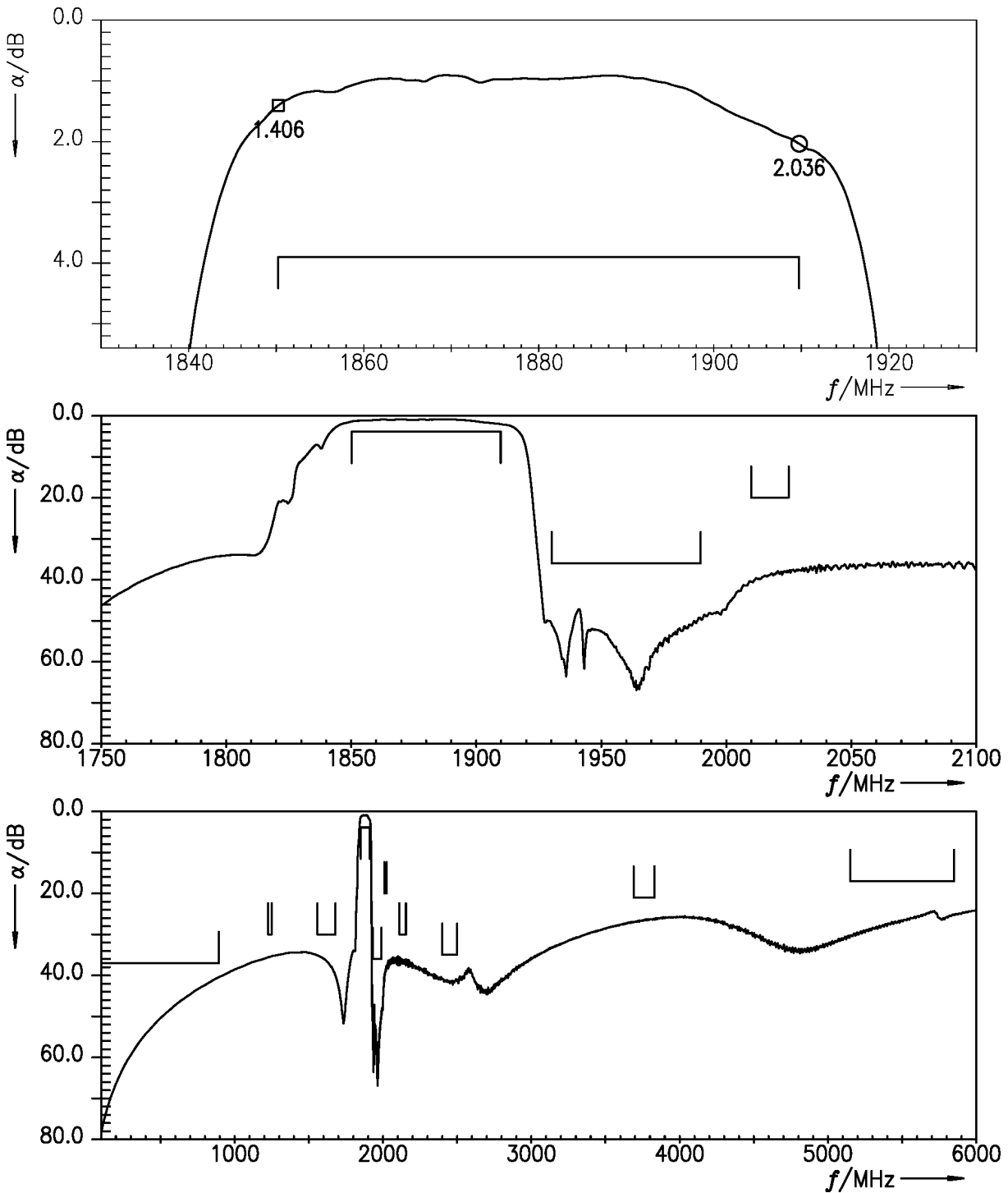


Figure 4: Attenuation TX – ANT.

8.2 ANT – RX

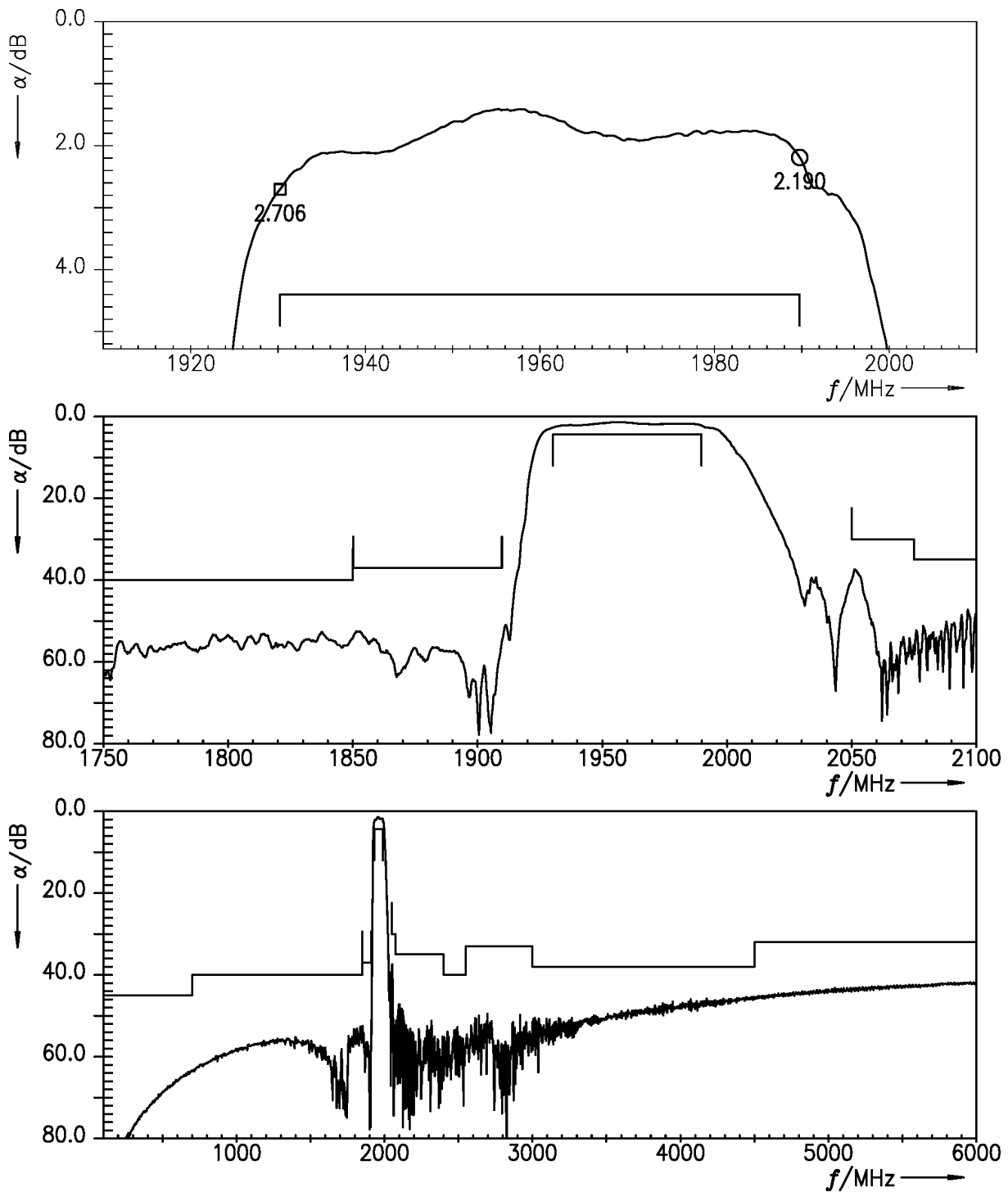


Figure 5: Attenuation ANT – RX.

8.3 TX – RX

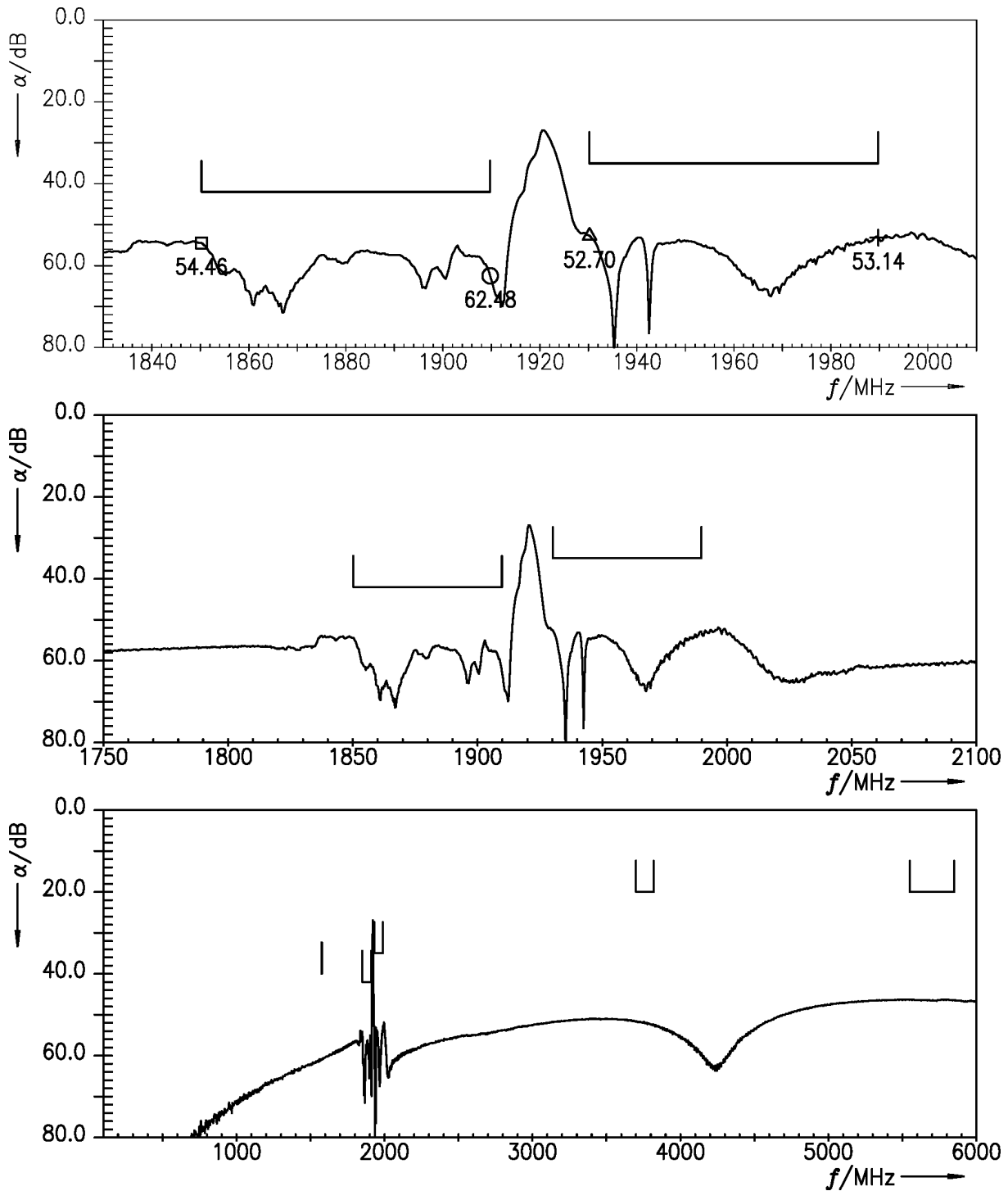


Figure 6: Isolation TX – RX.

9 Reflection coefficients

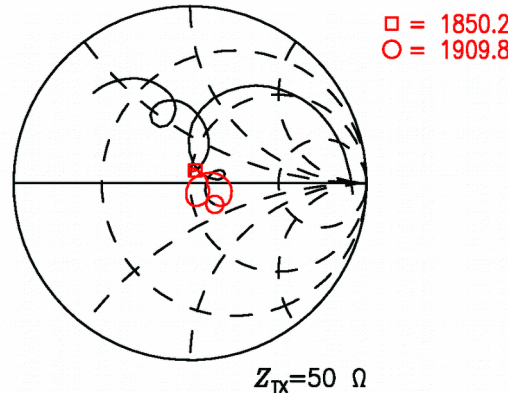
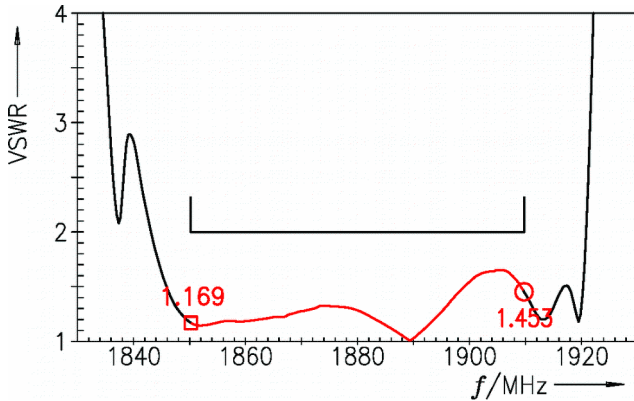


Figure 7: Reflection coefficient at TX port.

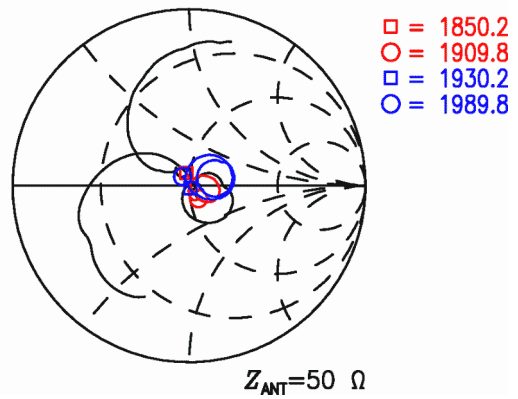
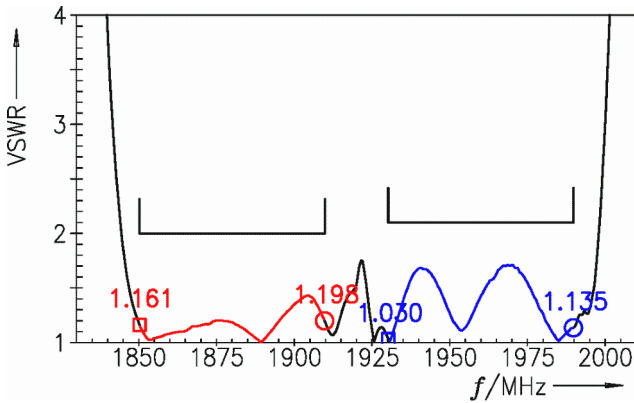


Figure 8: Reflection coefficient at ANT port.

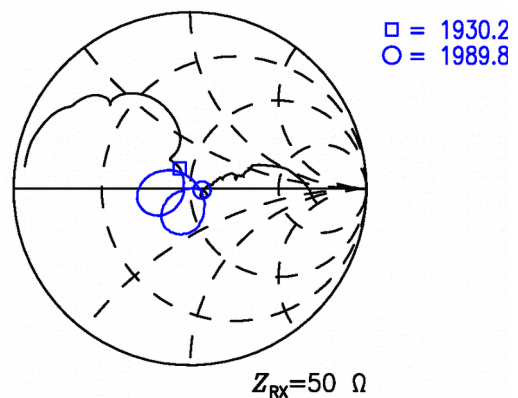
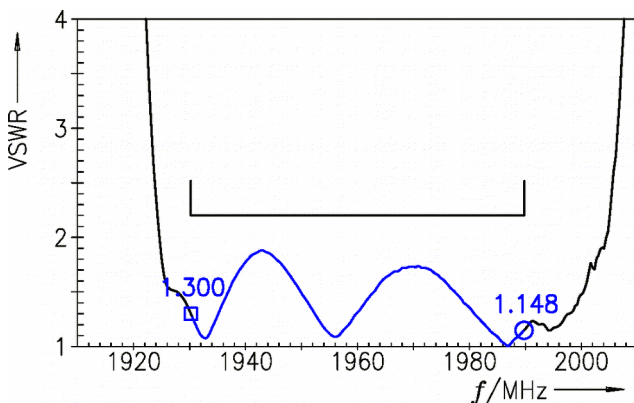


Figure 9: Reflection coefficient at RX port.



10 Packing material

10.1 Tape

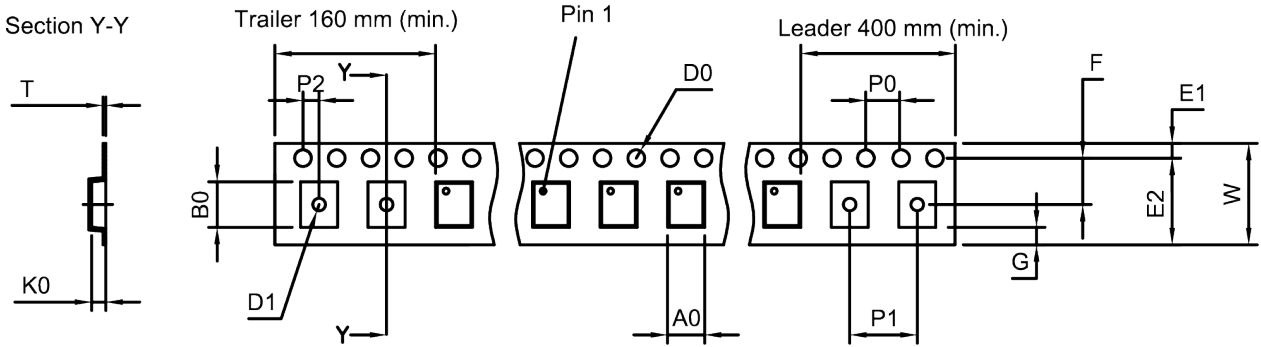


Figure 10: Drawing of tape (first-angle projection) with tape dimensions according to Table 1.

A <sub>0</sub>	1.62±0.05 mm	E <sub>2</sub>	6.25 mm (min.)	P <sub>1</sub>	4.0±0.1 mm
B <sub>0</sub>	2.04±0.05 mm	F	3.5±0.05 mm	P <sub>2</sub>	2.0±0.05 mm
D <sub>0</sub>	1.5+0.1/-0 mm	G	0.75 mm (min.)	T	0.25±0.05 mm
D <sub>1</sub>	0.8±0.05 mm	K <sub>0</sub>	0.62±0.05 mm	W	8.0±0.1 mm
E <sub>1</sub>	1.75±0.1 mm	P <sub>0</sub>	4.0±0.1 mm		

Table 1: Tape dimensions.

10.2 Reel with diameter of 180 mm

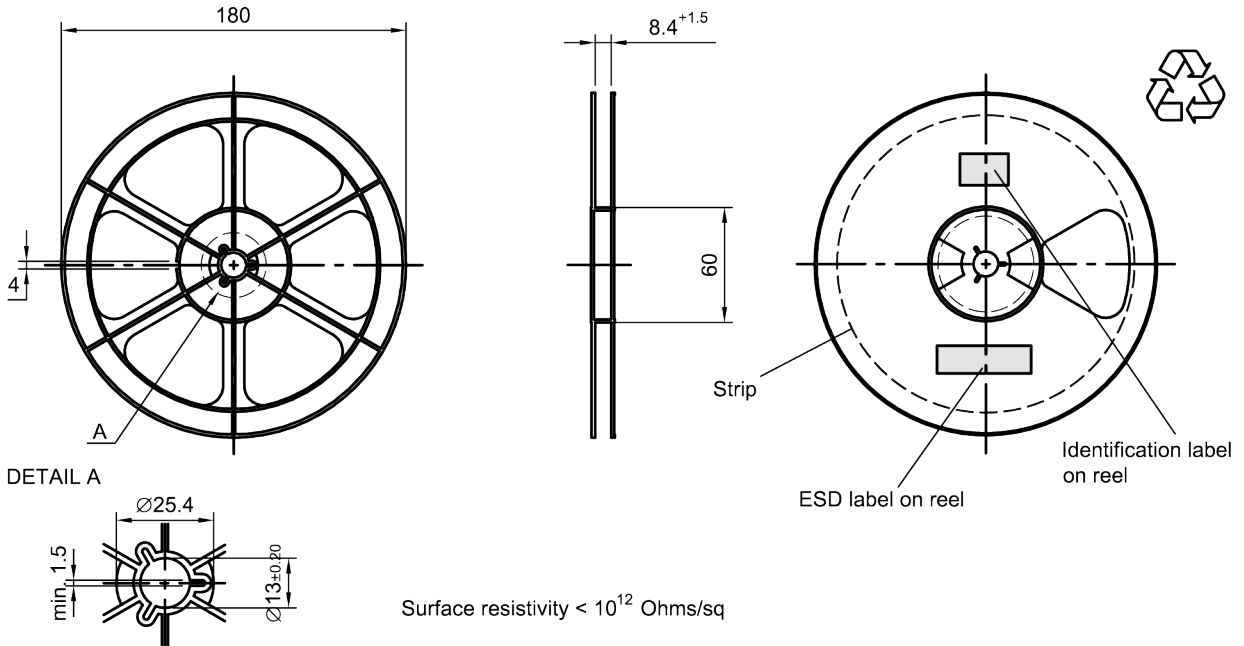


Figure 11: Drawing of reel (first-angle projection) with diameter of 180 mm.

Dimensions [mm]

X = 220+5

Y = 235+5

Sealing area 10±3

Printing on vacuumbag

Vacuumbag

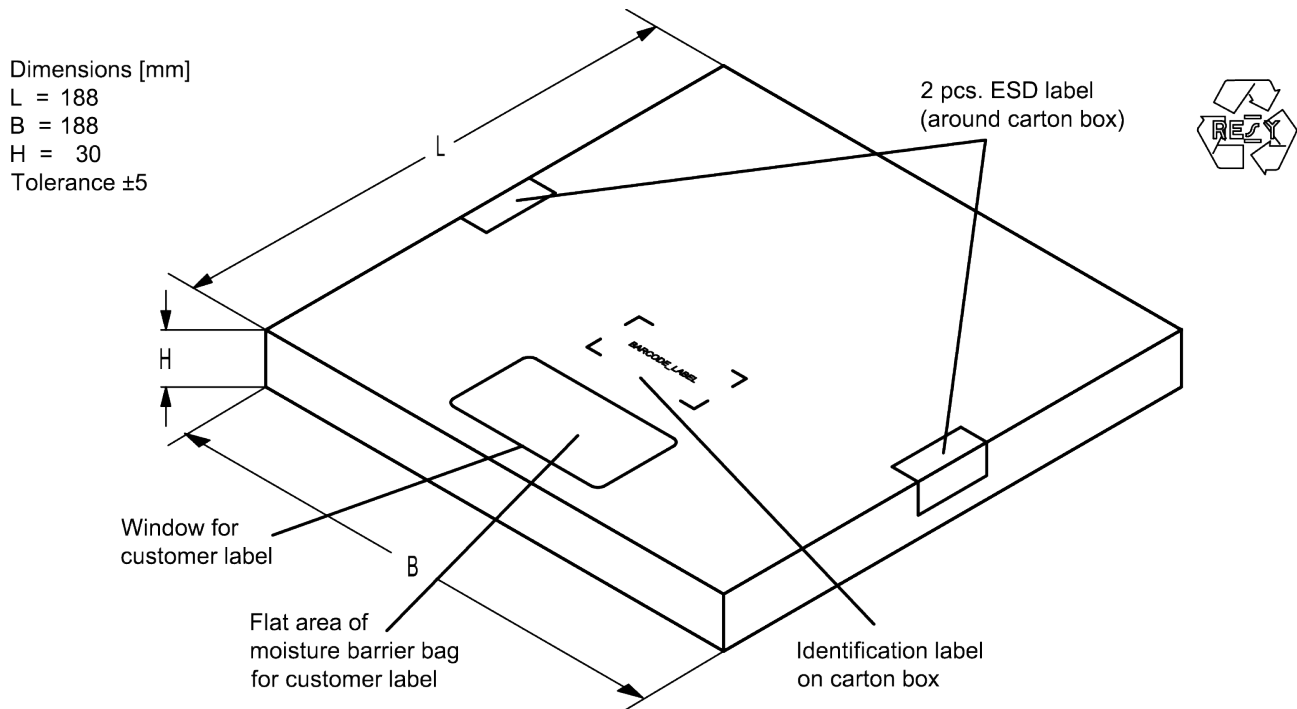
Sealing area

Drypack in vacuumbag

Identification label on vacuumbag

Humidity indicator in vacuumbag

Figure 12: Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.



**Figure 13:** Drawing of folding box for reel with diameter of 180 mm.

## 11 Marking

Products are marked with product type number and lot number encoded according to Table 2:

### ■ Type number:

The 4 digit type number of the ordering code, e.g., B3xxxxB**1234**xxxx,  
is encoded by a special BASE32 code into a 3 digit marking.

Example of decoding type number marking on device in decimal code.  
**16J** => **1234**  
 $1 \times 32^2 + 6 \times 32^1 + 18 (=J) \times 32^0 =$  **1234**  
 The BASE32 code for product type B4431 is 4AF.

### ■ Lot number:

The last 5 digits of the lot number, e.g., **12345**,  
are encoded based on a special BASE47 code into a 3 digit marking.

Example of decoding lot number marking on device in decimal code.  
**5UY** => **12345**  
 $5 \times 47^2 + 27 (=U) \times 47^1 + 31 (=Y) \times 47^0 =$  **12345**

Adopted BASE32 code for type number			
Decimal value	Base32 code	Decimal value	Base32 code
0	0	16	G
1	1	17	H
2	2	18	J
3	3	19	K
4	4	20	M
5	5	21	N
6	6	22	P
7	7	23	Q
8	8	24	R
9	9	25	S
10	A	26	T
11	B	27	V
12	C	28	W
13	D	29	X
14	E	30	Y
15	F	31	Z

Adopted BASE47 code for lot number			
Decimal value	Base47 code	Decimal value	Base47 code
0	0	24	R
1	1	25	S
2	2	26	T
3	3	27	U
4	4	28	V
5	5	29	W
6	6	30	X
7	7	31	Y
8	8	32	Z
9	9	33	b
10	A	34	d
11	B	35	f
12	C	36	h
13	D	37	n
14	E	38	r
15	F	39	t
16	G	40	v
17	H	41	\
18	J	42	?
19	K	43	{
20	L	44	}
21	M	45	<
22	N	46	>
23	P		

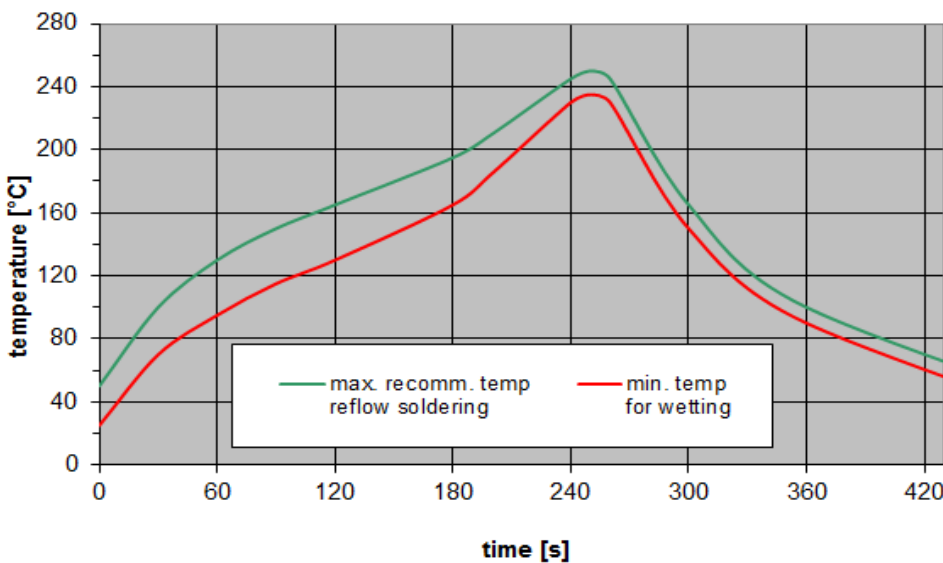
**Table 2:** Lists for encoding and decoding of marking.

**12 Soldering profile**

The recommended soldering process is in accordance with IEC 60068-2-58 – 3<sup>rd</sup> edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
T > 220 °C	30 s to 70 s
T > 230 °C	min. 10 s
T > 245 °C	max. 20 s
T ≥ 255 °C	–
peak temperature $T_{peak}$	250 °C +0/-5 °C
wetting temperature $T_{min}$	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature T	measured at solder pads

**Table 3:** Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).



**Figure 14:** Recommended reflow profile for convection and infrared soldering – lead-free solder.

## 13 Annotations

### 13.1 Matching coils

See TDK inductor pdf-catalog <http://www.tdk.co.jp/tefe02/coil.htm#aname1> and Data Library for circuit simulation <http://www.tdk.co.jp/etvcl/index.htm>.

### 13.2 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

### 13.3 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

## 14 Cautions and warnings

### 14.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under [www.rf360jv.com/orderingcodes](http://www.rf360jv.com/orderingcodes).

### 14.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

### 14.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

### 14.4 Package information

#### Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

#### Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Dimensions do not include burrs.

#### Projection method

Unless otherwise specified first-angle projection is applied.

## 15 Important notes

The following applies to all products named in this publication:

1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out **that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application**. As a rule, RF360 Europe GmbH and its affiliates are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an RF360 product with the properties described in the product specification is suitable for use in a particular customer application.
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